



Statement of Materials, Construction

LEAD-FREE -- 64L QFP -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element/Compound)	CAS Number	Material Mass (grams)	Material Weight % (of Total Pkg.)	Material Weight % (of Component)
1	Leadframe	Copper Alloy	0.18432	Cu	7440-50-8	0.18299	24.69	99.28
				Cr	7440-47-3	0.00041	0.05	0.22
				Sn	7440-31-5	0.00046	0.06	0.25
				Zn	7440-66-6	0.00046	0.06	0.25
2	Die	Silicon Chip	0.01002	Si	7440-21-3	0.01002	1.35	99.99
3	Die Attach Material	Conductive Epoxy	0.00794	Silver (Ag)	7440-22-4	0.00603	0.81	76.00
				Functionalized Urethane	Proprietary	0.00064	0.09	8.00
				Diester Resin	Proprietary	0.00083	0.11	10.50
				Epoxy Resin	Proprietary	0.00044	0.06	5.50
4	Wire	Gold	0.00779	Au	7440-57-5	0.00779	1.05	99.99
5	Lead Finish	Tin	0.00408	Sn	7440-31-5	0.00408	0.55	100
6	Encapsulation	Epoxy Resin	0.52712	Fused Silica	60676-86-0	0.45860	61.87	87.00
				Epoxy Resin	Proprietary	0.03953	5.33	7.50
				Phenol Resin	Proprietary	0.02899	3.91	5.50
Total Package Weight =			0.74127					

Note: Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%